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TITLE: NI-200z LEAD FORM	DOCUMENT NO: 98ARH98435A	REV: F
	STANDARD: NON-JEDEC	
	SOT1813-1	05 FEB 2016



NOTES:

1. CONTROLLING DIMENSION: INCHES
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
3. DIMENSION "H" (PACKAGE COPLANARITY): THE BOTTOM OF LEADS AND REFERENCE PLANE "T" MUST BE COPLANAR WITHIN DIM "H".

SYLE 1:

- PIN 1. DRAIN
- PIN 2. GATE
- PIN 3. SOURCE

DIM	INCH		MILLIMETER		DIM	INCH		MILLIMETER	
	MIN	MAX	MIN	MAX		MIN	MAX	MIN	MAX
A	.180	— .190	4.572	— 4.83	Y	.020	.040	0.508	1.016
B	.140	— .150	3.556	— 3.81	Z	---	R .020	---	R 0.508
C	.082	— .116	2.083	— 2.946	bbb	.010		0.254	
D	.047	— .053	1.194	— 1.346	ccc	.015		0.381	
E	.004	— .010	0.102	— 0.254	—	—	—	—	—
F	.004	— .006	0.102	— 0.152	—	—	—	—	—
H	.000	— .004	0.000	— 0.102	—	—	—	—	—
K	.050	— .090	1.270	— 2.286	—	—	—	—	—
M	.197	— .203	5.004	— 5.156	—	—	—	—	—
N	.177	— .183	4.496	— 4.648	—	—	—	—	—
R	.147	— .153	3.734	— 3.886	—	—	—	—	—
S	.157	— .163	3.988	— 4.140	—	—	—	—	—

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